ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® INCONTRIBUTION	Composition Dec 2005. IPC, Bannockt and Pan-American co	c <b>laration</b> ourn, Illinois. <i>A</i> opyright conve	All rights reserved u ntions.	nder both	This docume level parts, th	ent is a declaration er	on of the substance acompasses all lo	es within the man wer level materials	afacturer lister for which the	d item. Note: e manufacture	if the item is an as er has engineering	ssembly with low responsibility.
	IPC Web Site for Information on IPC-1752 Standard Form Type			*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information							
upplier Information												
Company name* Company			nique ID Un			Unique ID Authority			Respo	Response Date*		
onsemi					2023-06-08							
Contact Name Title - Contact			ct		]	Phone - Contact* Email - Contact*			ıtact*			
Product-Env-Stewards Prod			Product Enviro Compliance			NA			Prod	Product-Env-Stewards@onsemi.com		
Authorized Representative* Title - Representat			sentative		Phone - Representative* Email - Representative*							
Product-Env-Stewards Product En			ro Compliance		NA Product-Env-Stewards@onsemi.com					m		
Requester Item Number	Mfr Item			Mfr Item Name		Effective Date	Version	Manufacturing Site		Weight*	UOM	Unit Type
	STK672	STK672-632AN-E Stepping motor dr		river		2023-06-08	VN2			3380.0	mg	Each
Ianufacturing Proccess Inf	ormation						-					
Terminal Plating / Grid A	Terminal Plating / Grid Array Material Terminal Base A		Alloy J	J-STD-020 MSI	ASL Rating Peak F		k Process Body Temperature Max Time at Peak		t Peak Tempe	rature Num	ber of Reflow Cyc	cles
Matte Tin (Sn) - annealed CU		CU Alloy	I	NA		0	С	30	sec	onds 3		
omments												
or more information regarding m	aterial composition	please refer to	page 3									

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chro	HS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead b), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl thalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).									
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, itsuppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or written agreement, the warranty rights and/or remedies of Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.											
<b>RoHS Declaration *</b> 4 - Item(s	) does not contain RoHS restricted subst	ances per the definition above except for se	elected exempt	ions Supplier Acceptance	* Accepted						
Exemption: 7c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature R	astislav Drska	Le									

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

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Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Ceramic Substrate	1190.24	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		7.0224	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		46.1813	mg
			В	Nickel (Ni)	7440-02-0		2.0234	mg
			Supplier	Acrylic resins	Proprietary Data		0.8332	mg
			Supplier	Copper (Cu)	7440-50-8		81.4124	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7		0.5951	mg
			Supplier	Aluminum (Al)	7429-90-5		1052.1721	mg
Chip Parts	32.37	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		0.0032	mg
			Supplier	Silver (Ag)	7440-22-4		0.6603	mg
			Supplier	Epoxy resins	129915-35-1		0.2557	mg
			Supplier	Tin (Sn)	7440-31-5		1.1524	mg
			Supplier	Magnesium Monoxide (MgO)	1309-48-4		0.1651	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.6862	mg
			Supplier	Ceramic	12013-47-7, 12047- 27-7		6.1244	mg
			Supplier	Palladium (Pd)	7440-05-3		0.0486	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0129	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		20.4352	mg
			В	Nickel (Ni)	7440-02-0		1.5602	mg
			А	Lead Oxide (PbO)	1317-36-8	7c	0.0874	mg
			Supplier	Copper (Cu)	7440-50-8		1.1783	mg
Die	4.95	mg	Supplier	Silicon (Si)	7440-21-3		4.9401	mg
			Supplier	Polyimide	Proprietary Data		0.0099	mg
Lead Frame	417.81	mg	Supplier	Iron (Fe)	7439-89-6		0.4178	mg
			Supplier	Copper (Cu)	7440-50-8		417.2668	mg
			Supplier	Phosphorus (P)	7723-14-0		0.1253	mg
Mold Compound-Black	1723.57	mg		Brominated epoxy resin	proprietary data		34.4714	mg
			Supplier	Phenolic Resin	Proprietary Data		120.6499	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		34.4714	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		1206.4989	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		327.4783	mg
Plating	0.94	mg	Supplier	Tin (Sn)	7440-31-5		0.582	mg

			В	Nickel (Ni)	7440-02-0	0.358	mg
Solder Ball	8.89	mg	Supplier	Silver (Ag)	7440-22-4	0.248	mg
			Supplier	Tin (Sn)	7440-31-5	8.5913	mg
			В	Antimony (Sb)	7440-36-0	0.0071	mg
			Supplier	Copper (Cu)	7440-50-8	0.0436	mg
Wire Bond	1.23	mg	Supplier	Silicon (Si)	7440-21-3	0.0037	mg
			Supplier	Aluminum (Al)	7429-90-5	1.2263	mg